





Clause	<ol style="list-style-type: none"> 1. Printed Circuit Board Assembly (PCBA) Data Package <ol style="list-style-type: none"> a. Certificate of Compliance per RL-SR-001 - Supplier Quality Manual b. All manufacturer reports/results. <ol style="list-style-type: none"> i. The following shall be provided if the PCB was produced or procured by the PCBA subcontractor. <ol style="list-style-type: none"> 1. The PCBA manufacturer shall include the items listed below: <ol style="list-style-type: none"> a. Micro Sections <ol style="list-style-type: none"> i. Final micro-sections coupon analysis shall be provided to Rocket Lab ii. Coupon design shall be in accordance to IPC-2221 and the specified finished PCB characteristics. b. If applicable, a complete list of the test results performed at the bare-board level or on the unpotted and potted harnesses. c. Results of ionic contamination testing d. All deviation and waiver reports, including all MRB actions taken on the PCBs or materials. e. All raw material reports and supplier certifications, if any c. The PCBA Data Package shall comprise the following document: <ol style="list-style-type: none"> i. As Built List (ABL) <ol style="list-style-type: none"> 1. Part number and Lot or Date code Information for all components shall be recorded to the PCBA batch ii. Material certificates <ol style="list-style-type: none"> 1. Material used shall be traceable to the manufacturer's lot number through date code iii. List of Assembly Materials (solder, ink, wire, flux, etc.) <ol style="list-style-type: none"> 1. Lot and expiration date records shall be kept and provided upon request of Rocket Lab iv. Deviations from drawings and parts lists and objective evidence for the approval v. Copies of all redlined drawings and parts lists vi. Evidence of approval from Rocket Lab for all non-conformances with disposition of Use As Is and/or Repair vii. Rework documentation shall be kept and provided upon request of Rocket Lab viii. Surface Mount Process Reflow Profile shall be kept and provided upon request of Rocket Lab ix. X-Ray Images of CGA, BGA and BTC components shall be kept and provided upon request of Rocket Lab x. High resolution photo documentation of all sides of the completed PCBA shall be kept and provided upon request of Rocket Lab xi. xii. 2. <ol style="list-style-type: none"> a.
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